

FIG. 1

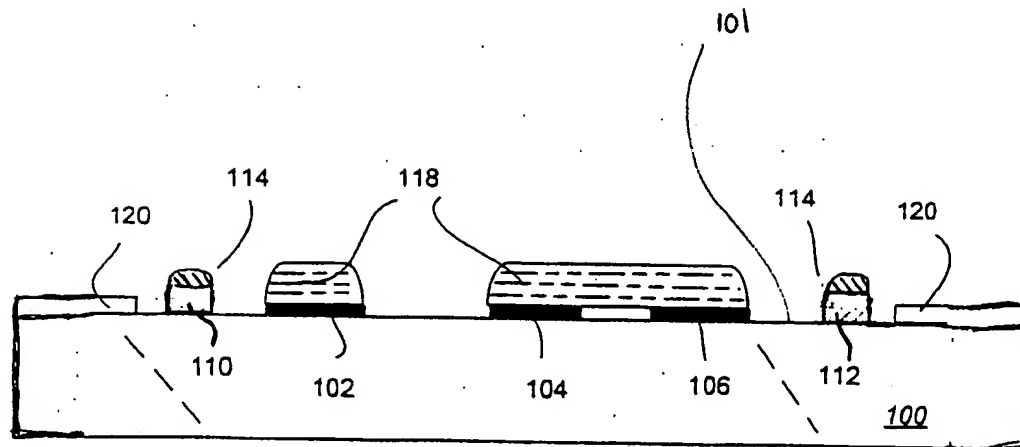


FIG. 2

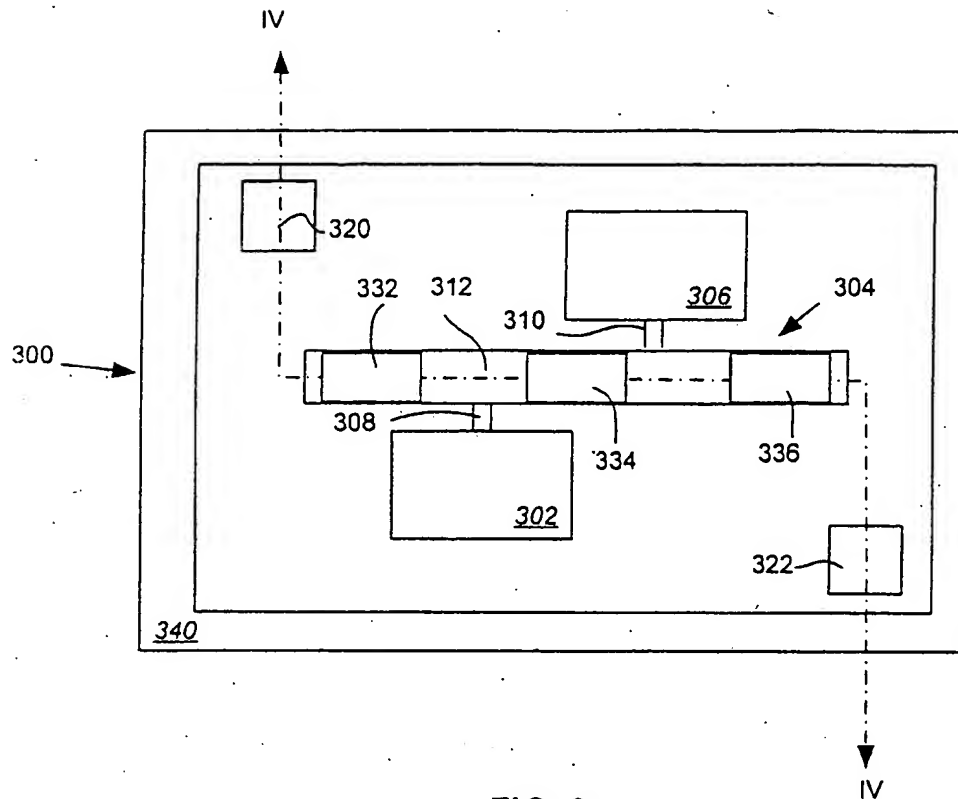


FIG. 3

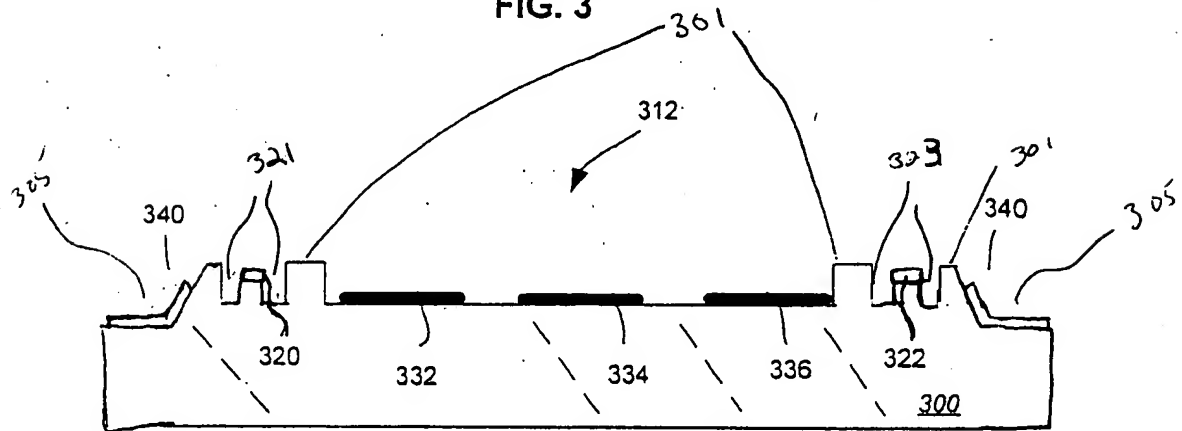
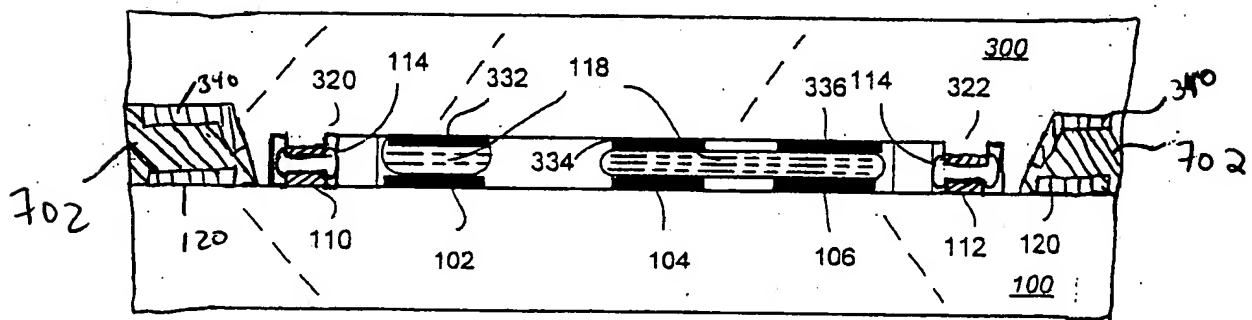
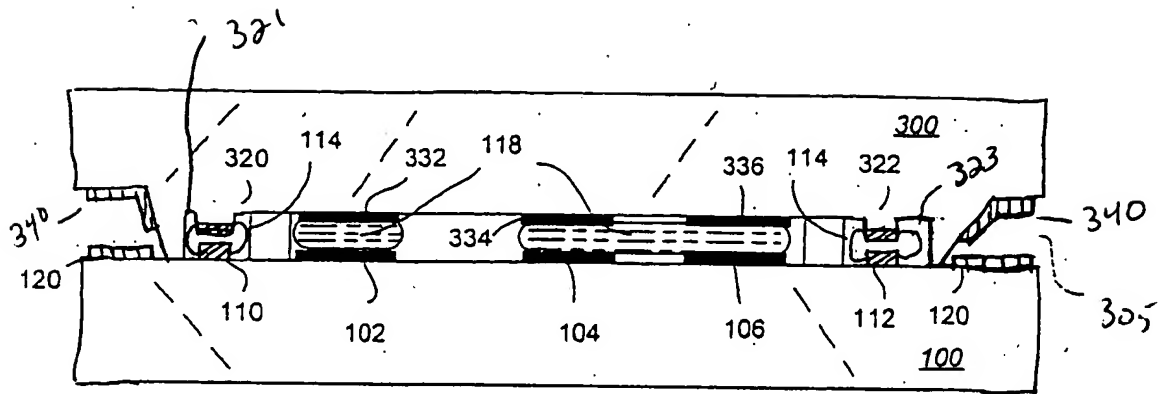


FIG. 4



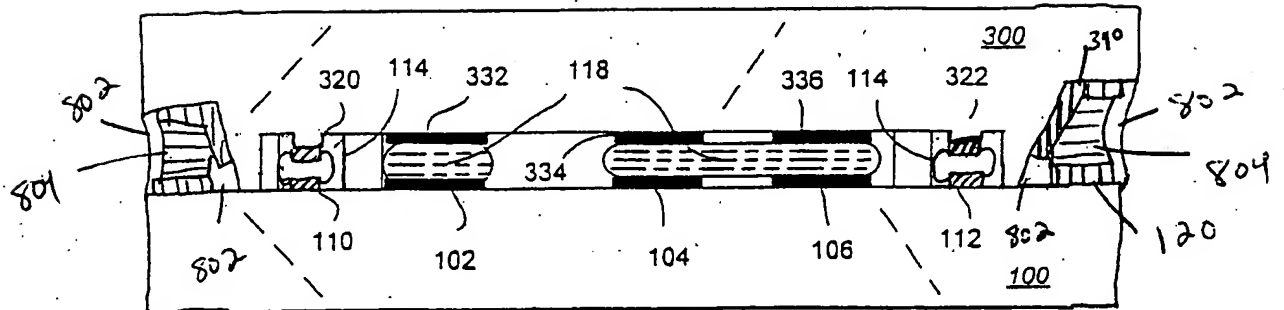
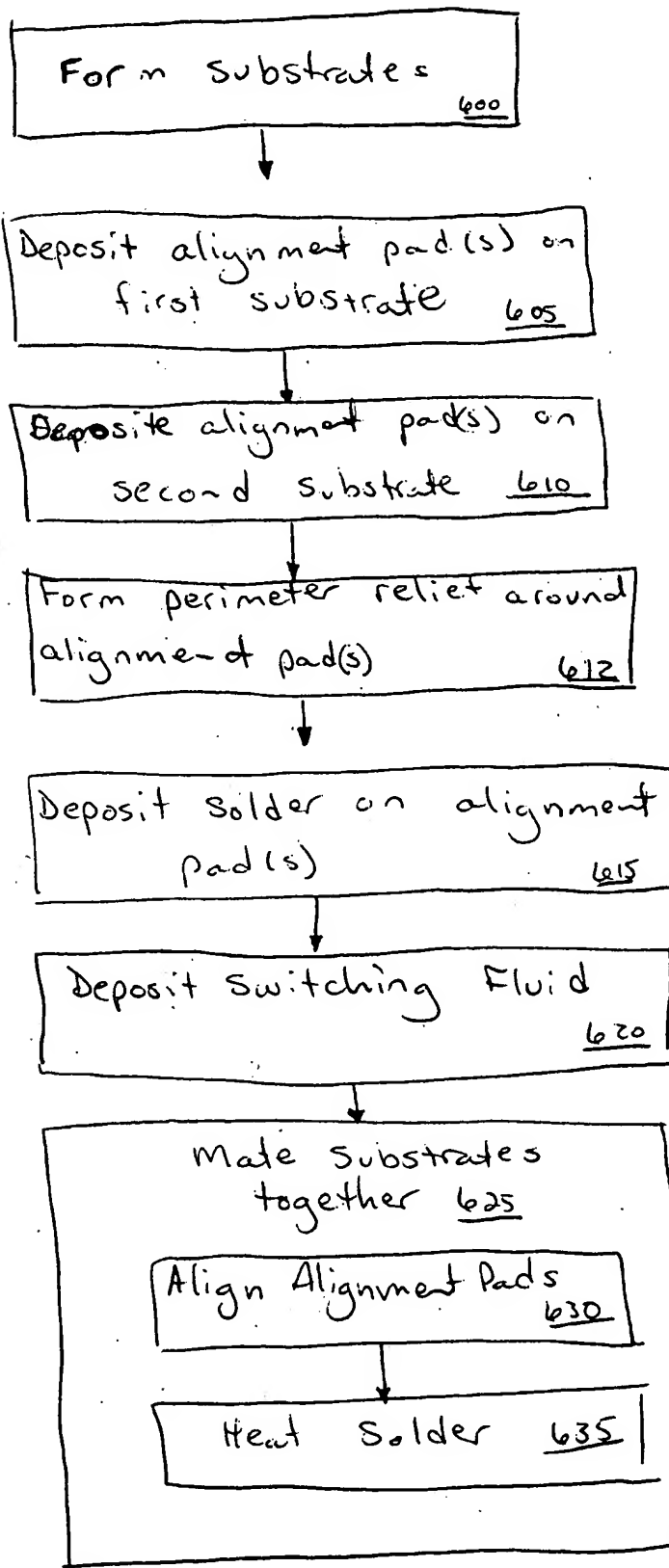


FIG. 7



Form perimeter ring  
around switching device  
in substrate(s)

640

Deposit solderable contact  
surface in perimeter  
seal ring

645

Deposit Solder paste and  
uncured epoxy in perimeter  
seal ring

650

Reflow Solder pastes and  
uncured epoxy

655

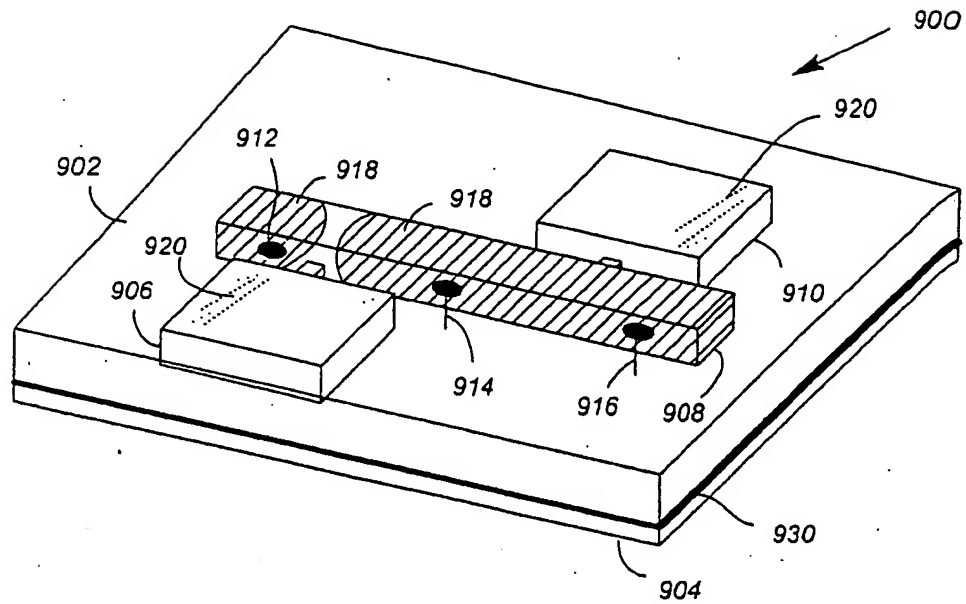


FIG. 9

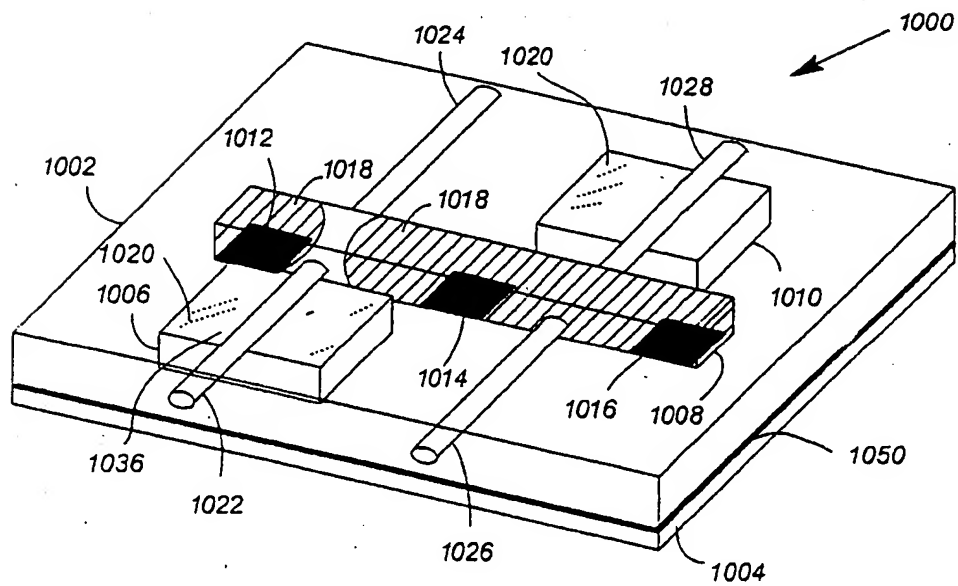


FIG. 10